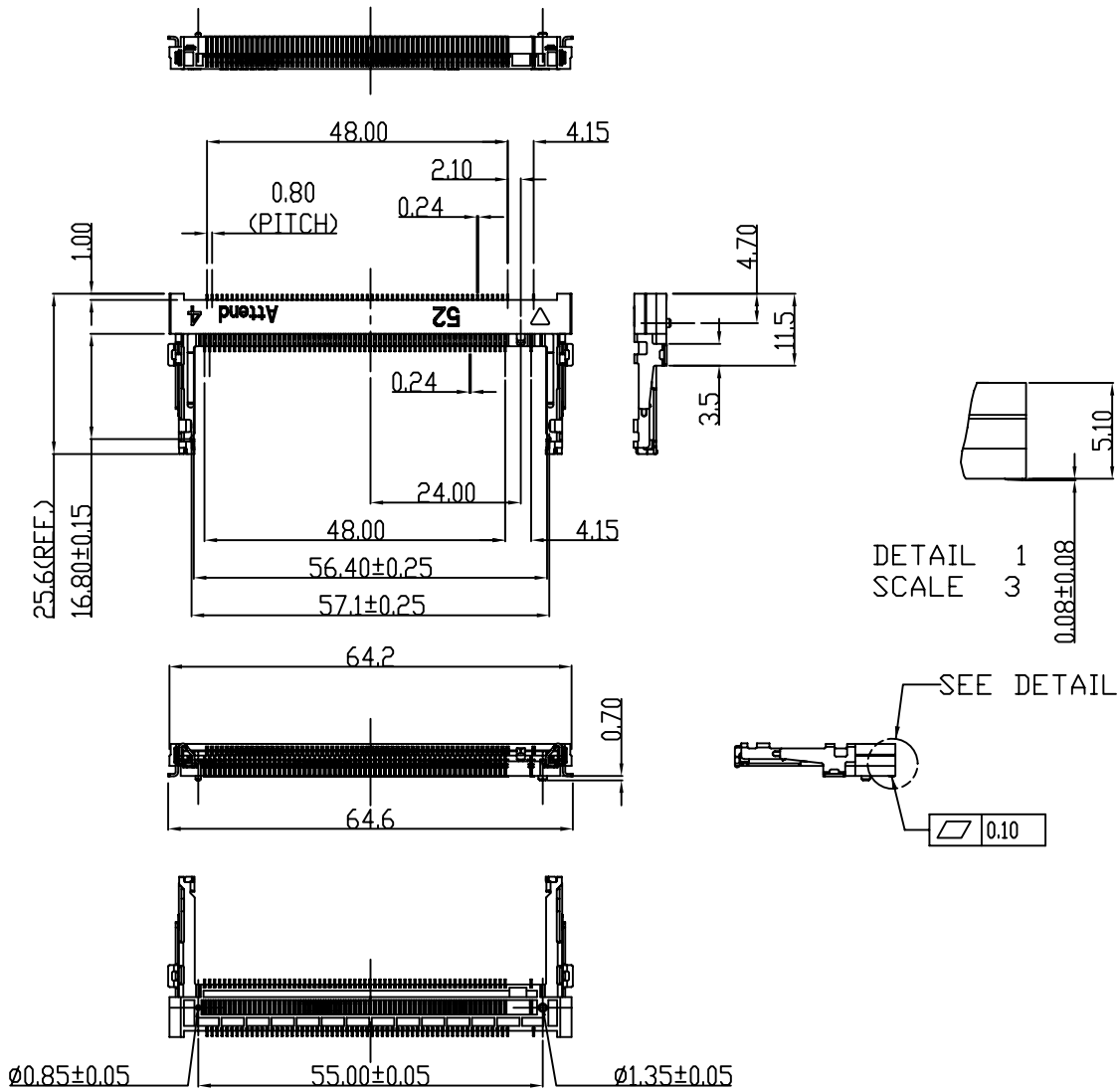


PRODUCT NO.	ITEM	PART NAME	Q'TY	MATERIAL	PLATING
114B-52B00-R02	1	BODY	1	LCP	
	3	CONTACT	124	PHOSPHOR BRONZE	GOLD 3u"
	4	LATCH	2	STAINLESS	



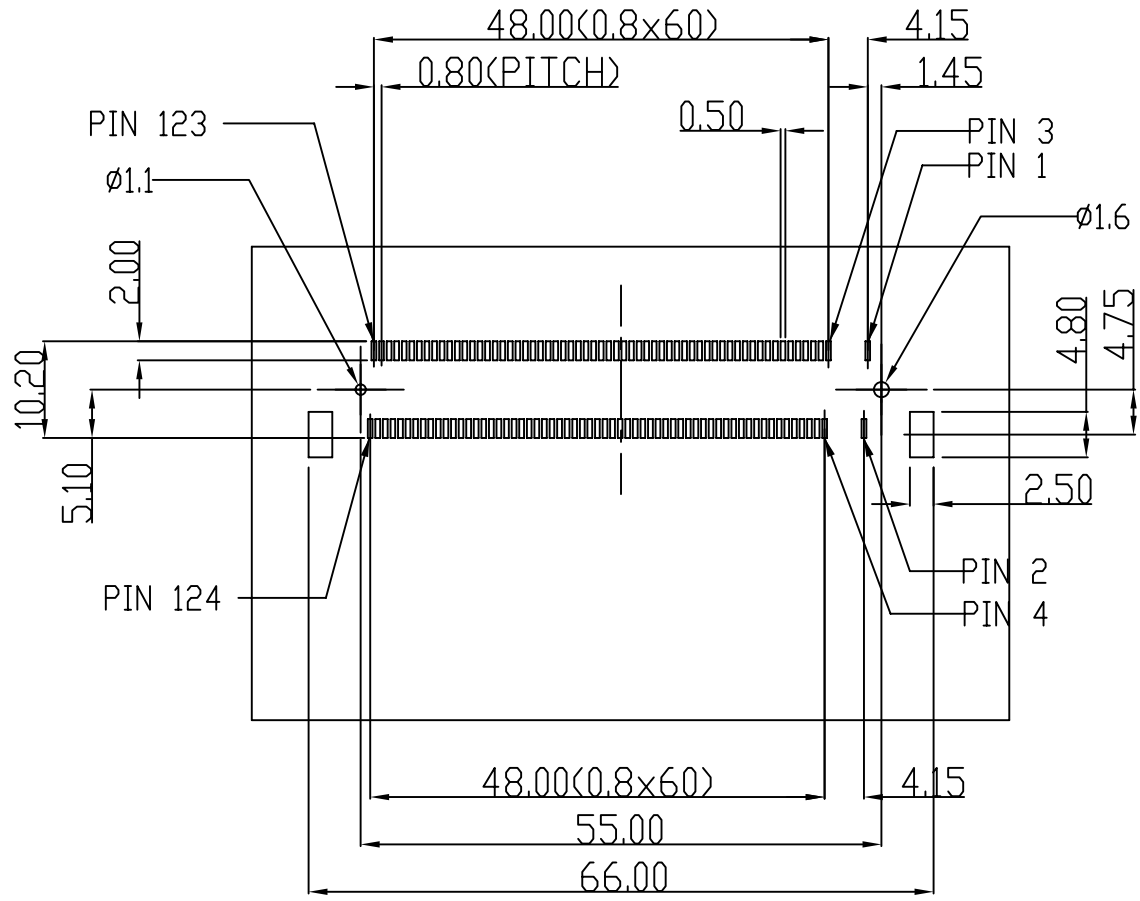
Plastic Body : LCP, Color Black.
 Contact: Phosphor Bronze Alloy (C5191R-H)
 Contact area: Gold 3 micro inches
 Solder area: Matte Tin Plated
 All under-plated Ductile Nickel 50 micro inches (Min.)
 Latch : SUS304R-1/2H, Matte Tin Plated
 Contact Resistance: 30 mΩ (Max)
 Insulation Resistance: 500 MΩ (Max.)
 Dielectric Withstanding Voltage:
 Mate connectors; apply 250V AC at 60 Hz(rms.)
 Contact Normal Force: 50 gf per pin (Min.)
 soldering heat: 260°C
 Rating Voltage: 25V AC
 Rating Current: 0.3A(Max.)/(1PIN)
 Operating Temperature: -40°C to +90°C
 Storage Temperature: -40°C to +90°C

114B-52 B 0 0-R02
 1 2 3 4

- 1.Stand off
s/o:5.2mm
- 2.Contact Plating
B:3u" Gold Plating
- 3.Color
0:Black
- 4.RoHS

UNLESS OTHERWISE SPECIFIED TOLERANCE	
ANG.	±5
0.	±0.3
.0	±0.25
.00	±0.20
SCALE:	AS SHOWN
UNIT:	mm
DRAWN	Willis
DATE	2009/09/28
CHECKED	Angel
DATE	2009/09/28
APPROVED	Ken
DATE	2009/07/06
DRAWN NAME:	Mini PCI Socket
stand off	5.2mm, Metal grounding type
PRODUCT NO.	114B-52B00-R02
FILE NAME:	114B-52B00-R02_B_3

REV.	DESCRIPTION	DATE
1	Revise: Latch Matte Tin Plated	2009/09/28
2	Revise: Layout Peg	2009/07/06



RECOMMEND PC BOARD LAYOUT

						UNLESS OTHERWISE SPECIFIED TOLERANCE				
						ANG. ±5°				
						0. ±0.3				
						.0 ±0.25				
						.00 ±0.20				
						SCALE: AS SHOWN	UNIT: mm			
						DRAWN Willis	2009/09/28	DRAWN NAME: Mini PCI Socket		
						CHECKED Angel	2009/09/28	stand off 5.2mm, Metal grounding type		
						APPROVED Ken	2009/09/28	PRODUCT NO. 114B-52B00-R02		
						SIZE A4	REV.	FILE NAME: 114B-52B00-R02_B_3		
REV.	DESCRIPTION					DATE				
1	Revise: Latch Matte Tin Plated					2009/09/28				
2	Revise: Layout Peg					2009/07/06				